

## 2.0X1.25mm SMD CHIP LED LAMP

APTK2012SEC SUPER BRIGHT ORANGE

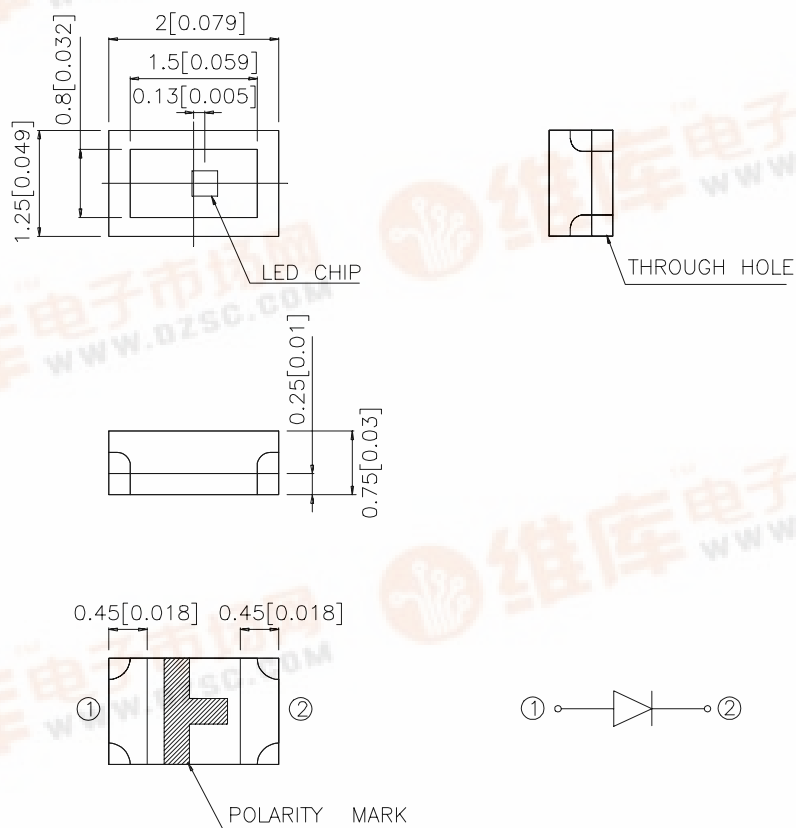
### Features

- 2.0mmX1.25mm SMT LED, 0.75mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.

### Description

The Super Bright Orange source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

### Package Dimensions



### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.1$  (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	I <sub>v</sub> (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APTK2012SEC	SUPER BRIGHT ORANGE (InGaAlP)	WATER CLEAR	110	280	100°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Super Bright Orange	610		nm	I <sub>F</sub> =20mA
λ <sub>D</sub>	Dominate Wavelength	Super Bright Orange	601		nm	I <sub>F</sub> =20mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Super Bright Orange	29		nm	I <sub>F</sub> =20mA
C	Capacitance	Super Bright Orange	30		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Super Bright Orange	2.0	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Super Bright Orange		10	uA	V <sub>R</sub> = 5V

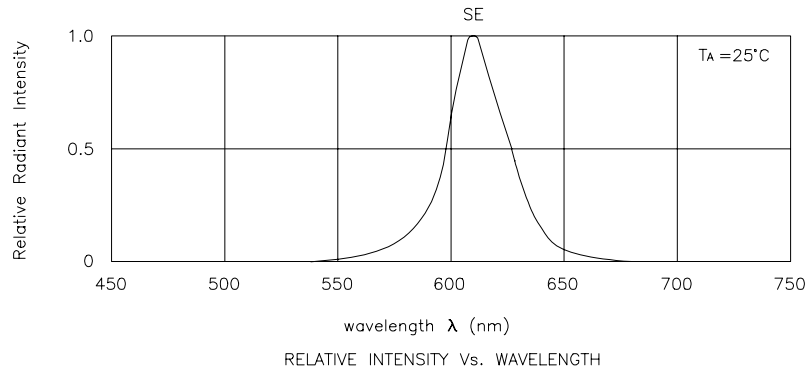
## Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

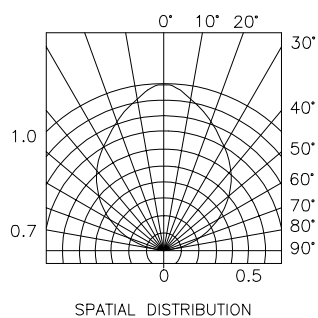
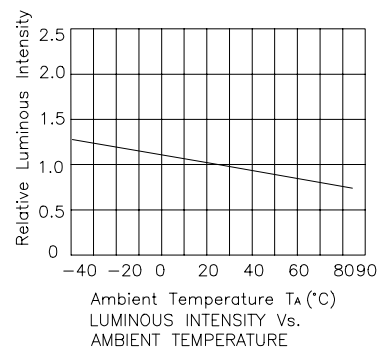
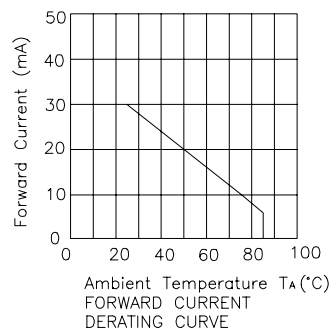
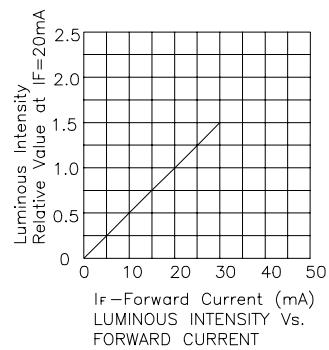
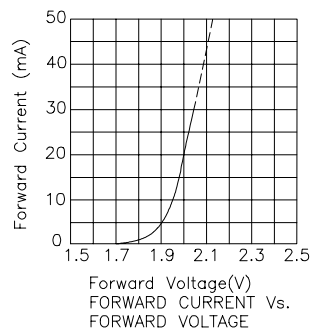
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

# Kingbright



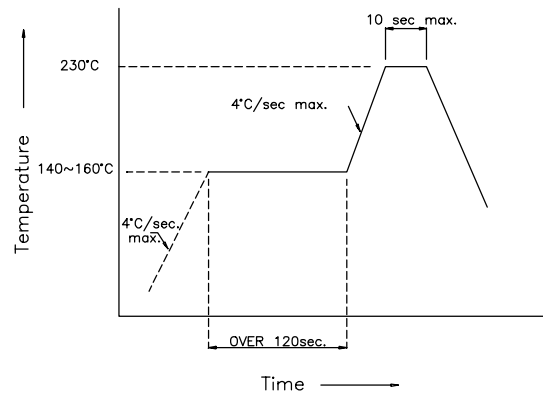
## Super Bright Orange APTK2012SEC



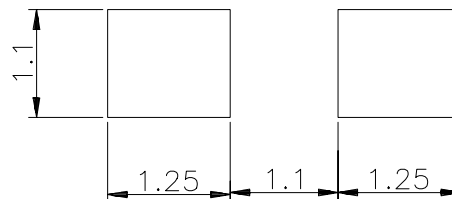
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### SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)

